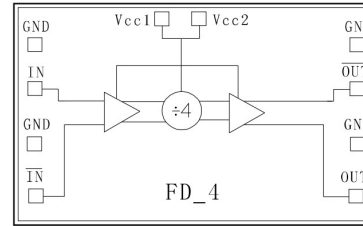


Performance

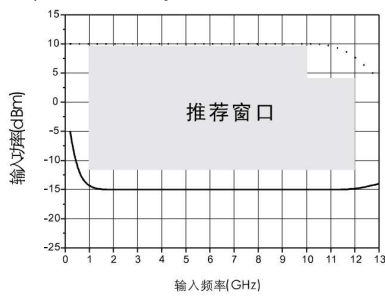
- Frequency: DC-12GHz
- Operating Voltage: +5V
- Output Power: -3dBm
- Chip size: 1.60*0.75*0.1mm

Function Diagram

Electrical Specifications (Ta=+25°C, Vcc=+5V)

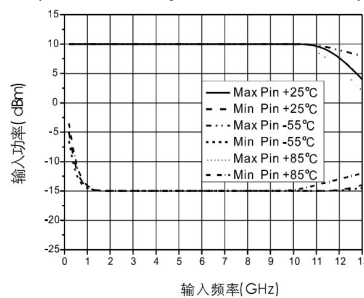
Parameter	Operating Condition	Min	Typical	Max	Unit
Max Input Frequency		12	13	-	GHz
Min Input Frequency	Sin-wave input	-	0.2	0.5	GHz
Input Power Range	Fin=1~10GHz	-10	> -12	+10	dBm
	Fin=10~12GHz	-15	> -12	+6	dBm
Output Power	Fin=5GHz	-4.5	-3	-	dBm
	Fin=8GHz	-7	-4	-	dBm
Reverse Leakage	OUT, $\overline{\text{OUT}}$, Terminated	-	60	-	dB
SSB Phase noise (100KHz offset)	Pin=0dBm, Fin=4.8GHz	-	-146	-	dBc/Hz
Operating Current		80	95	110	mA

Test Curves (Die chip testing)

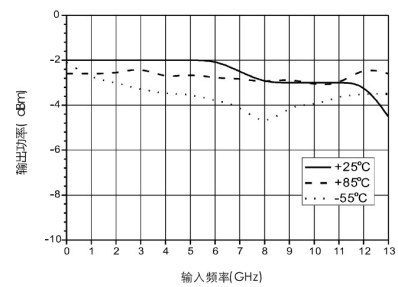
Input Sensitivity Window T=+25°C



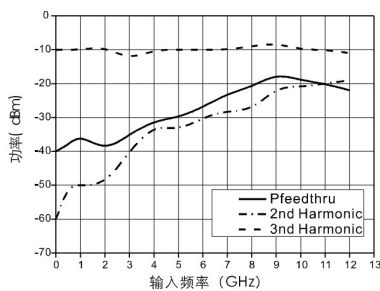
Input Sensitivity Window vs. Temp



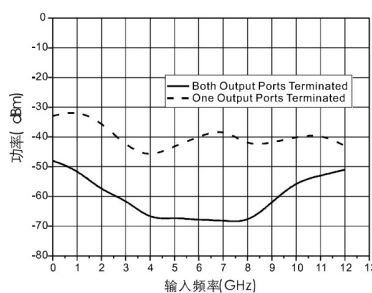
Output Power vs. Temp



Output Harmonic, Pin=0dBm, T=+25°C

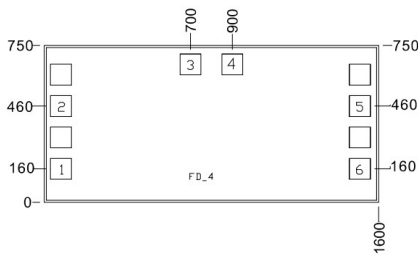


Reverse Leakage, Pin=0dBm, T=+25°C


Absolute Max Ratings

Vcc	+5.5Vdc
Pin	13dBm
Tj	175°C
Tstg	-65~+150°C
To	-55~+125°C
HBM	Class 1A

Outline Size



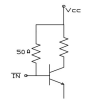
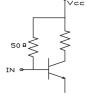
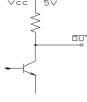
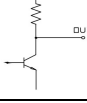
Note:

1. Unit: μm
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated, size: $100 \times 100 (\mu\text{m})$
5. Don't bonding on thru holes
6. Tolerance: $\pm 50 \mu\text{m}$

Typical Operating Current

Vcc (V)	Icc (mA)
4.75	85
5.0	95
5.25	105

Bonding Pads Definition

Number	Symbol	Description	Equivalent Circuits
1	$\overline{\text{IN}}$	RF input (external block capacitor needed) 180° phase different with Pad 2.	
2	IN	RF input (external block capacitor needed)	
3,4	Vcc 2, Vcc 1	Current +5V	-
5	$\overline{\text{OUT}}$	Frequency divider signal output (external block capacitor needed) 180° phase different with Pad 6.	
6	OUT	Frequency divider signal output (external block capacitor needed)	

Assembly

